

SIEMENS

3.3V 256 K x 16-Bit EDO-DRAM

HYB 314175BJ-50/-55/-60

3.3V 256 K x 16-Bit EDO-DRAM (Low power version with Self Refresh)

HYB 314175BJL-50/-55/-60

Preliminary Information

- 262 144 words by 16-bit organization
- 0 to 70 °C operating temperature
- Fast access and cycle time
- $\overline{\text{RAS}}$ access time:
 - 50 ns (-50 version)
 - 55 ns (-55 version)
 - 60 ns (-60 version)
- $\overline{\text{CAS}}$ access time:
 - 13ns (-50 & -55 version)
 - 15 ns (-60 version)
- Cycle time:
 - 89 ns (-50 version)
 - 94 ns (-55 version)
 - 104 ns (-60 version)
- Hype page mode (EDO) cycle time
 - 20 ns (-50 & -55 version)
 - 25 ns (-60 version)
- High data rate
 - 50 MHz (-50 & -55 version)
 - 40 MHz (-60 version)
- Single + 3.3 V (± 0.3 V) supply with a built-in VBB generator
- Low Power dissipation
 - max. 450 mW active (-50 version)
 - max. 432 mW active (-55 version)
 - max. 378 mW active (-60 version)
- Standby power dissipation
 - 7.2 mW standby (TTL)
 - 3.6 mW max. standby (CMOS)
 - 0.72 mW max. standby (CMOS) for Low Power Version
- Output unlatched at cycle end allows two-dimensional chip selection
- Read, write, read-modify write, CAS-before-RAS refresh, RAS-only refresh, hidden-refresh and hyper page (EDO) mode capability
- 2 CAS / 1 WE control
- Self Refresh (L-Version)
- All inputs and outputs TTL-compatible
- 512 refresh cycles / 16 ms
- 512 refresh cycles / 128 ms Low Power Version only
- Plastic Packages:
 - P-SOJ-40-1 400mil width

The HYB 314175BJ/BJL is the new generation dynamic RAM organized as 262 144 words by 16-bit. The HYB 314175BJ/BJL utilizes CMOS silicon gate process as well as advanced circuit techniques to provide wide operation margins, both internally and for the system user. Multiplexed address inputs permit the HYB 314175BJ/BJL to be packed in a standard plastic 400mil wide P-SOJ-40-1 package. This package size provides high system bit densities and is compatible with commonly used automatic testing and insertion equipment. System oriented features include Self Refresh (L-Version), single + 3.3 V (± 0.3 V) power supply, direct interfacing with high performance logic device families.

Ordering Information

Type	Ordering Code	Package	Description
HYB 314175BJ-50	Q67100 - Q2148	P-SOJ-40-1	3.3 V 50 ns 256 Kx16 EDO-DRAM
HYB 314175BJ-55	on request	P-SOJ-40-1	3.3 V 55 ns 256 Kx16 EDO-DRAM
HYB 314175BJ-60	Q67100 - Q2149	P-SOJ-40-1	3.3 V 60 ns 256 Kx16 EDO-DRAM
HYB 314175BJL-50	on request	P-SOJ-40-1	3.3 V 50 ns 256 Kx16 EDO- DRAM
HYB 314175BJL-55	on request	P-SOJ-40-1	3.3 V 55 ns 256 Kx16 EDO- DRAM
HYB 314175BJL-60	on request	P-SOJ-40-1	3.3 V 60 ns 256 Kx16 EDO-DRAM

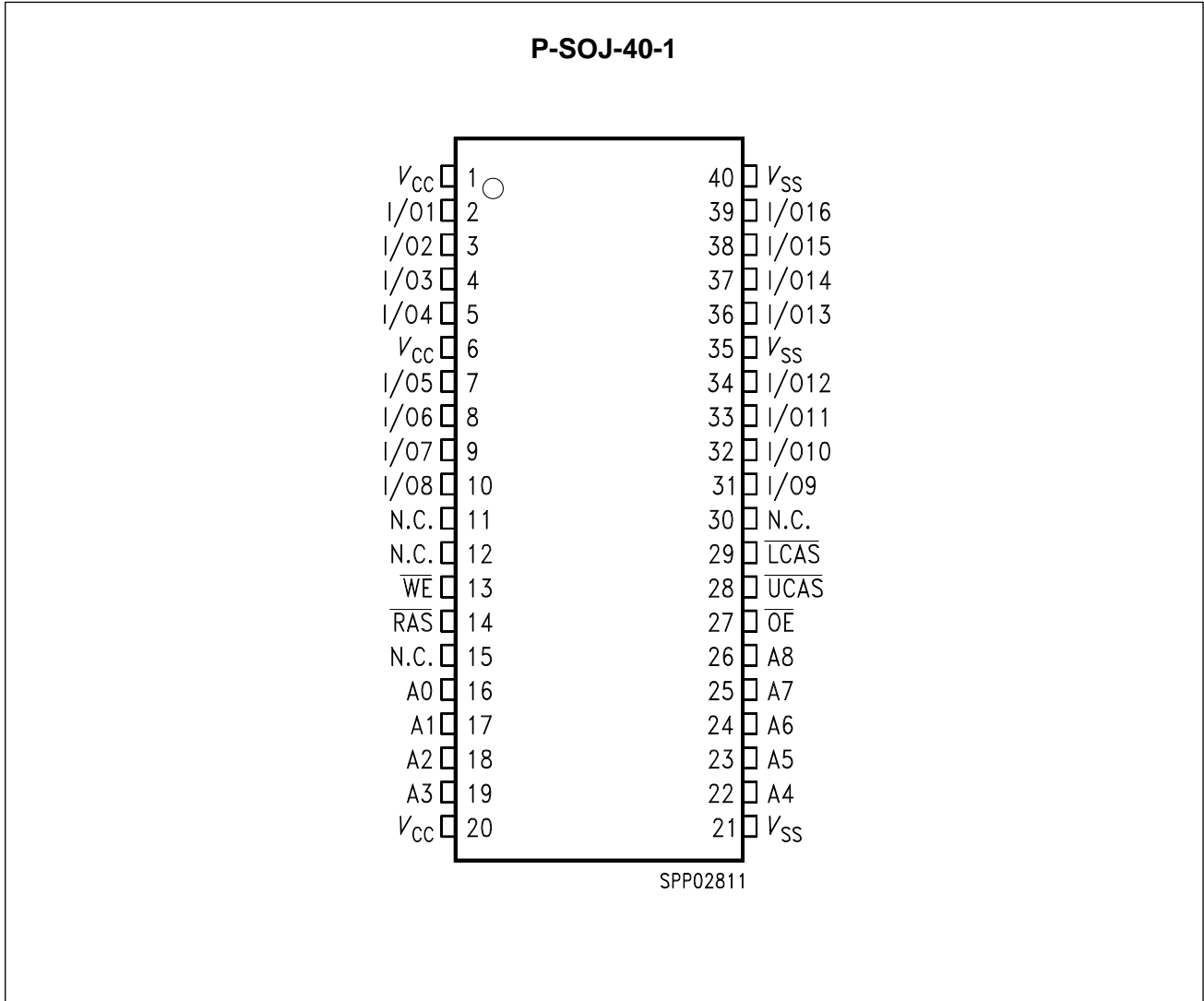
Truth Table

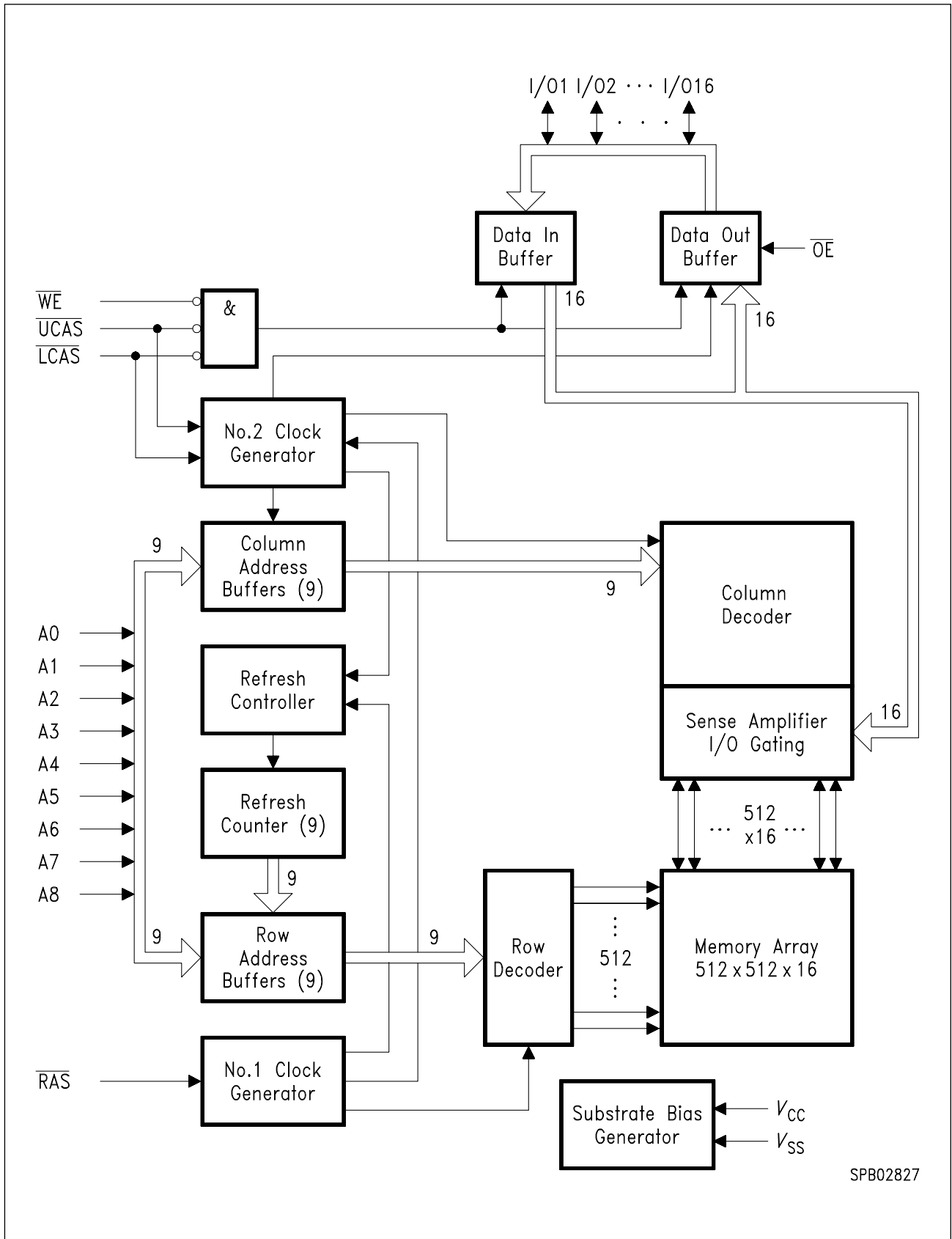
$\overline{\text{RAS}}$	$\overline{\text{LCAS}}$	$\overline{\text{UCAS}}$	$\overline{\text{WE}}$	$\overline{\text{OE}}$	I/O1-I/O8	I/O9-I/O16	Operation
H	H	H	H	H	High-Z	High-Z	Standby
L	H	H	H	H	High-Z	High-Z	Refresh
L	L	H	H	L	Dout	High-Z	Lower byte read
L	H	L	H	L	High-Z	Dout	Upper byte read
L	L	L	H	L	Dout	Dout	Word read
L	L	H	L	H	Din	Don't care	Lower byte write
L	H	L	L	H	Don't care	Din	Upper byte write
L	L	L	L	H	Din	Din	Word write
L	L	L	H	H	High-Z	High-Z	

Pin Names

A0-A8	Address Inputs
$\overline{\text{RAS}}$	Row Address Strobe
$\overline{\text{UCAS}}, \overline{\text{LCAS}}$	Column Address Strobe
$\overline{\text{WE}}$	Read/Write Input
$\overline{\text{OE}}$	Output Enable
I/O1 – I/O16	Data Input/Output
V_{CC}	Power Supply (+ 3.3 V)
V_{SS}	Ground (0 V)
N.C.	No Connection

Pin Configuration
(top view)





SPB02827

Block Diagram

Absolute Maximum Ratings

Operating temperature range	0 to + 70 °C
Storage temperature range.....	– 55 to + 150 °C
Input/output voltage	– 1 to ($V_{CC} + 0.5, 4.6$) V
Power supply voltage.....	– 1 to + 4.6 V
Data out current (short circuit)	50 mA

Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage of the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

$T_A = 0$ to 70 °C; $V_{SS} = 0$ V; $V_{CC} = 3.3$ V \pm 0.3 V, $t_T = 2$ ns

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Input high voltage	V_{IH}	2.4	$V_{CC} + 0.5$	V	1
Input low voltage	V_{IL}	– 1.0	0.8	V	1
LVTTL Output high voltage ($I_{OUT} = - 2.0$ mA)	V_{OH}	2.4	–	V	1
LVTTL Output low voltage ($I_{OUT} = 2$ mA)	V_{OL}	–	0.4	V	1
LVC MOS Output high voltage ($I_{OUT} = - 100$ μ A)	V_{OH}	2.4	–	V	1
LVC MOS Output low voltage ($I_{OUT} = 100$ μ A)	V_{OL}	–	0.4	V	1
Input leakage current, any input (0 V < $V_{IN} < 7$ V, all other inputs = 0 V)	$I_{I(L)}$	– 10	10	μ A	1
Output leakage current (DO is disabled, 0 V < $V_{OUT} < V_{CC}$)	$I_{O(L)}$	– 10	10	μ A	1
Average V_{CC} supply current: -50 version -55 version -60 version	I_{CC1}	–	125 120 105	mA	2, 3, 4
Standby V_{CC} supply current ($\overline{RAS} = \overline{LCAS} = \overline{UCAS} = \overline{WE} = V_{IH}$)	I_{CC2}	–	2	mA	–
Average V_{CC} supply current during RAS-only refresh cycles: -50 version -55 version -60 version	I_{CC3}	–	125 120 105	mA	2, 4

DC Characteristics (cont'd)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Average V_{CC} supply current during hyper page mode (EDO) operation: -50 version -55 version -60 version	I_{CC4}	–	115 115 100	mA	2, 3, 4
Standby V_{CC} supply current ($\overline{RAS} = \overline{LCAS} = \overline{UCAS} = \overline{WE} = V_{CC} - 0.2 V$)	I_{CC5}	–	1	mA	1
Average V_{CC} supply current during CAS-before-RAS refresh mode: -50 version -55 version -60 version	I_{CC6}	–	125 120 105	mA	2, 4
Standby V_{CC} current (L-version) ($\overline{RAS} = \overline{LCAS} = \overline{UCAS} = \overline{WE} = V_{CC} - 0.2 V$)	I_{CC5}	–	200	μA	
Self Refresh Current (L-version) ($\overline{RAS}, \overline{LCAS}, \overline{UCAS} = 0.2V$ $A0 - A8 = V_{CC} - 0.2 V$ or $0.2 V$)	I_{CCS}	–	250	μA	

Capacitance

$T_A = 0$ to $70\text{ }^\circ C$; $V_{CC} = 3.3 V \pm 0.3 V$, $f = 1\text{ MHz}$

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input capacitance (A0 to A8)	C_{I1}	–	5	pF
Input capacitance ($\overline{RAS}, \overline{UCAS}, \overline{LCAS}, \overline{WE}, \overline{OE}$)	C_{I2}	–	7	pF
Output capacitance (I/O1 to I/O16)	C_{I0}	–	7	pF

AC Characteristics ^{5) 6)}

$T_A = 0$ to 70 °C; $V_{SS} = 0$ V; $V_{CC} = 3.3$ V \pm 0.3 V, $t_T = 2$ ns

Parameter	Symbol	Limit Values						Unit	Note
		-50		-55		-60			
		min	max	min	max	min	max		

Common Parameters

Random read or write cycle time	t_{RC}	89	–	94	–	104	–	ns	
RAS precharge time	t_{RP}	35	–	35	–	40	–	ns	
RAS pulse width	t_{RAS}	50	10k	55	10k	60	10k	ns	
CAS pulse width	t_{CAS}	8	10k	8	10k	10	10k	ns	
Row address setup time	t_{ASR}	0	–	0	–	0	–	ns	
Row address hold time	t_{RAH}	8	–	8	–	10	–	ns	
Column address setup time	t_{ASC}	0	–	0	–	0	–	ns	
Column address hold time	t_{CAH}	8	–	8	–	10	–	ns	
RAS to CAS delaytime	t_{RCD}	12	37	12	43	14	45	ns	
RAS to column address delay time	t_{RAD}	10	25	10	30	12	30	ns	
RAS hold time	t_{RSH}	13	–	13	–	15	–	ns	
CAS hold time	t_{CSH}	40	–	45	–	50	–	ns	
CAS to RAS precharge time	t_{CRP}	5	–	5	–	5	–	ns	
Transition time(rise and fall)	t_T	1	50	1	50	1	50	ns	7
Refresh period	t_{REF}	–	16	–	16	–	16	ms	
Refresh period (L-version)	t_{REF}	–	128	–	128	–	128	ms	

Read Cycle

Access time from RAS	t_{RAC}	–	50	–	55	–	60	ns	8, 9
Access time from CAS	t_{CAC}	–	13	–	13	–	15	ns	8, 9
Access time from column address	t_{AA}	–	25	–	25	–	30	ns	8,10
OE access time	t_{OEA}	–	13	–	13	–	15	ns	
Column address to RAS lead time	t_{RAL}	25	–	25	–	30	–	ns	
Read command setup time	t_{RCS}	0	–	0	–	0	–	ns	
Read command hold time	t_{RCH}	0	–	0	–	0	–	ns	11
Read command hold time ref. to RAS	t_{RRH}	0	–	0	–	0	–	ns	11
CAS to output inlow-Z	t_{CLZ}	0	–	0	–	0	–	ns	8

Parameter	Symbol	Limit Values						Unit	Note
		-50		-55		-60			
		min	max	min	max	min	max		
Output buffer turn-off delay from $\overline{\text{CAS}}$	t_{OFF}	0	13	0	13	0	15	ns	12
Output buffer turn-off delay from $\overline{\text{OE}}$	t_{OEZ}	0	13	0	13	0	15	ns	12
Data to $\overline{\text{OE}}$ low delay	t_{DZO}	0	–	0	–	0	–	ns	13
$\overline{\text{CAS}}$ high to data delay	t_{CDD}	10	–	10	–	13	–	ns	14
$\overline{\text{OE}}$ high to data delay	t_{ODD}	10	–	10	–	13	–	ns	14

Write Cycle

Write command hold time	t_{WCH}	8	–	8	–	10	–	ns	
Write command pulse width	t_{WP}	8	–	8	–	10	–	ns	
Write command setup time	t_{WCS}	0	–	0	–	0	–	ns	15
Write command to $\overline{\text{RAS}}$ lead time	t_{RWL}	13	–	13	–	15	–	ns	
Write command to $\overline{\text{CAS}}$ lead time	t_{CWL}	13	–	13	–	15	–	ns	
Data setup time	t_{DS}	0	–	0	–	0	–	ns	16
Data hold time	t_{DH}	8	–	8	–	10	–	ns	16
Data to $\overline{\text{CAS}}$ low delay	t_{DZC}	0	–	0	–	0	–	ns	13

Read-modify-Write Cycle

Read-write cycle time	t_{RWC}	118	–	122	–	138	–	ns	
$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ delay time	t_{RWD}	64	–	69	–	77	–	ns	15
$\overline{\text{CAS}}$ to $\overline{\text{WE}}$ delay time	t_{CWD}	27	–	27	–	32	–	ns	15
Column address to $\overline{\text{WE}}$ delay time	t_{AWD}	39	–	39	–	47	–	ns	15
$\overline{\text{OE}}$ command hold time	t_{OEH}	10	–	10	–	13	–	ns	

Hyper Page Mode (EDO) Cycle

Hyper page mode cycle time	t_{HPC}	20	–	20	–	25	–	ns	
$\overline{\text{CAS}}$ precharge time	t_{CP}	8	–	8	–	10	–	ns	
Access time from $\overline{\text{CAS}}$ precharge	t_{CPA}	–	27	–	27	–	32	ns	7
Output data hold time	t_{COH}	5	–	5	–	5	–	ns	
$\overline{\text{RAS}}$ pulse width in hyper page mode	t_{RAS}	50	200k	55	200k	60	200k	ns	
$\overline{\text{RAS}}$ hold time from $\overline{\text{CAS}}$ precharge	t_{RHCP}	27	–	27	–	32	–	ns	

Parameter	Symbol	Limit Values						Unit	Note
		-50		-55		-60			
		min	max	min	max	min	max		

Hyper Page Mode (EDO) Read-Modify-Write Cycle

Hyper page mode read/write cycle time	t_{PRWC}	58	–	58	–	68	–	ns	
$\overline{\text{CAS}}$ precharge to $\overline{\text{WE}}$ delay time	t_{CPWD}	41	–	41	–	49	–	ns	

$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh Cycle

$\overline{\text{CAS}}$ setup time	t_{CSR}	5	–	5	–	5	–	ns	
$\overline{\text{CAS}}$ hold time	t_{CHR}	10	–	10	–	10	–	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ precharge time	t_{RPC}	5	–	5	–	5	–	ns	
Write to $\overline{\text{RAS}}$ precharge time	t_{WRP}	10	–	10	–	10	–	ns	
Write to $\overline{\text{RAS}}$ hold time	t_{WRH}	10	–	10	–	10	–	ns	

$\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Counter Test Cycle

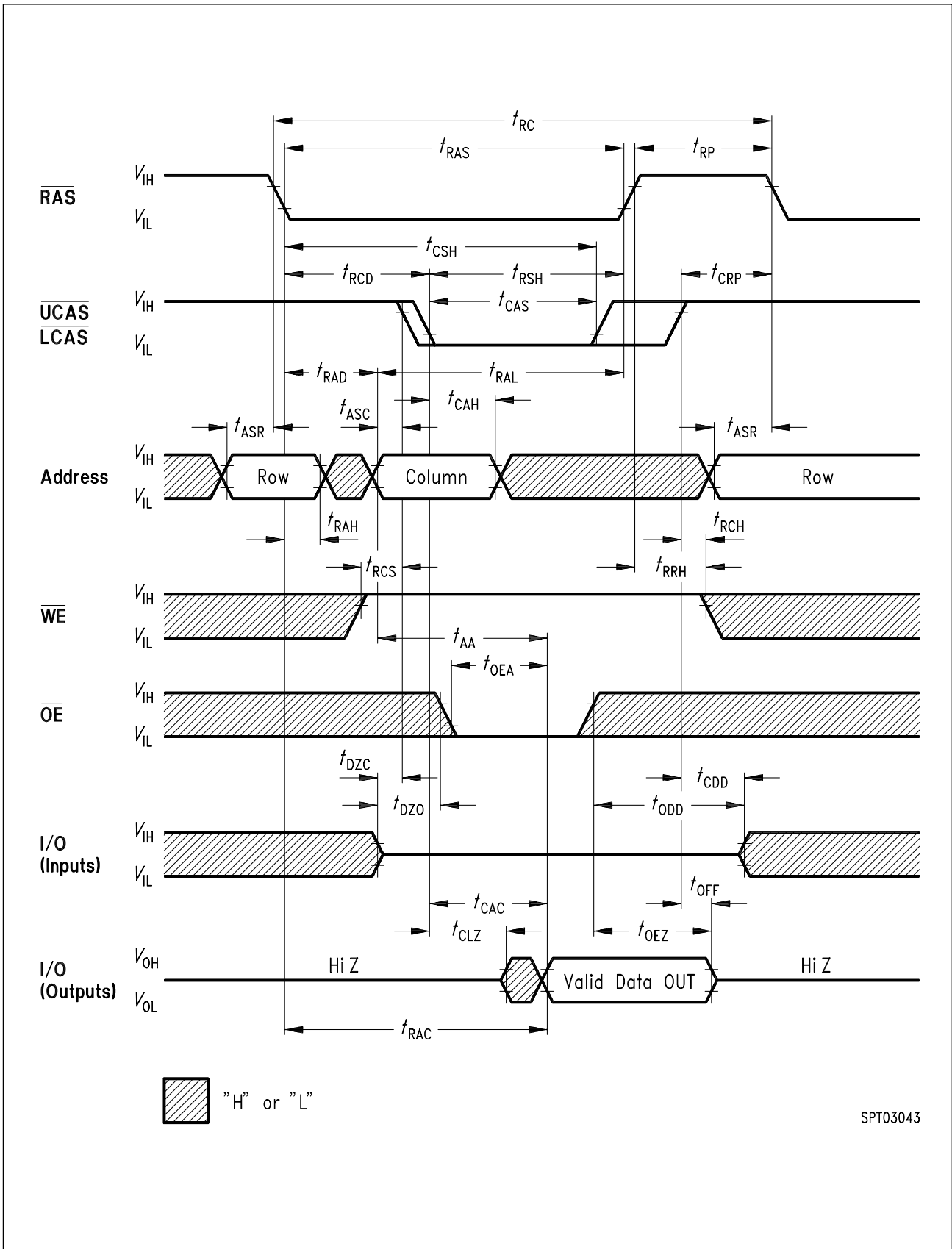
$\overline{\text{CAS}}$ precharge time	t_{CPT}	35	–	35	–	40	–	ns	
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Self Refresh Cycle (L-Version only)

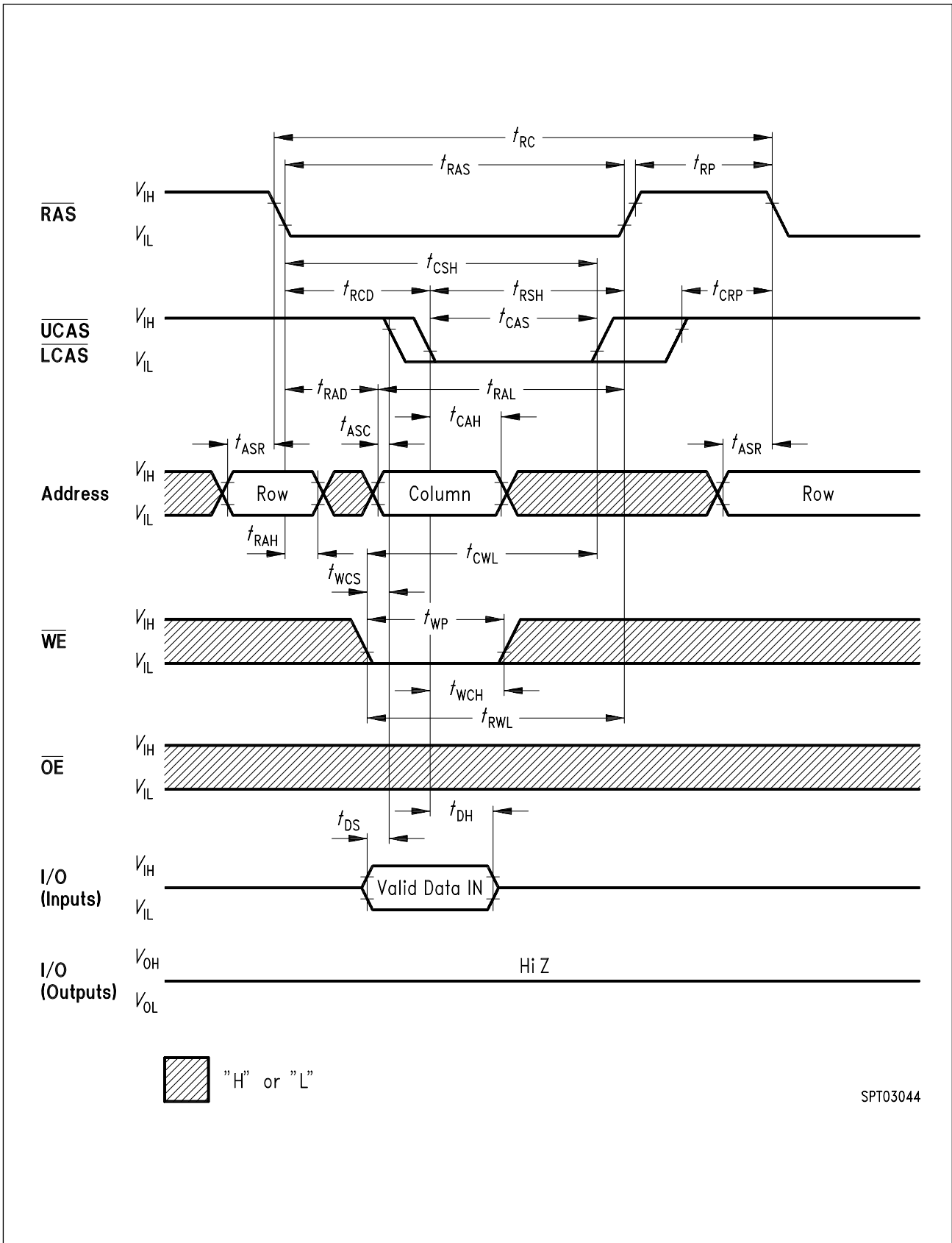
$\overline{\text{RAS}}$ pulse width	t_{RASS}	100	–	100	–	100	–	μs	
$\overline{\text{RAS}}$ precharge time	t_{RPS}	95	–	110	–	110	–	ns	
$\overline{\text{CAS}}$ hold time	t_{CHS}	– 50	–	– 50	–	– 50	–	ns	

Notes:

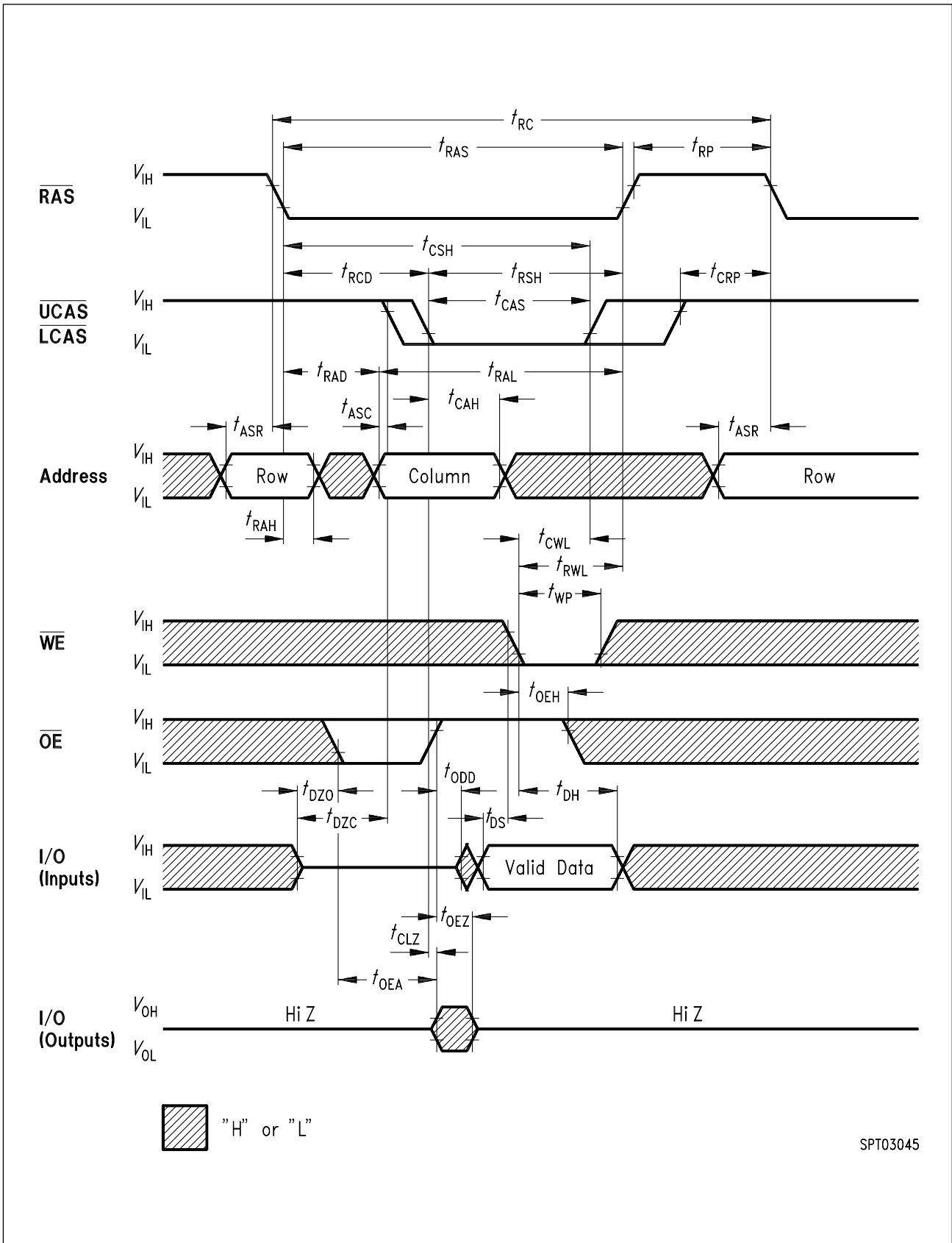
- 1) All voltages are referenced to V_{SS} .
- 2) I_{CC1} , I_{CC3} , I_{CC4} and I_{CC6} depend on cycle rate.
- 3) I_{CC1} and I_{CC4} depend on output loading. Specified values are obtained with the output open.
- 4) Address can be changed once or less while $RAS = V_{i1}$. In case of I_{CC4} it can be changed once or less during a hyper page mode (EDO) cycle
- 5) An initial pause of 200 μs is required after power-up followed by 8 \overline{RAS} cycles of which at least one cycle has to be a refresh cycle, before proper device operation is achieved. In case of using the internal refresh counter, a minimum of 8 \overline{CAS} -before- \overline{RAS} initialization cycles instead of 8 \overline{RAS} cycles are required.
- 6) AC measurements assume $t_T = 2$ ns.
- 7) $V_{IH (min.)}$ and $V_{IL (max.)}$ are reference levels for measuring timing of input signals. Transition times are also measured between V_{IH} and V_{IL} .
- 8) Measured with the specified current load and 100 pF at $V_{ol} = 0.8$ V and $V_{oh} = 2.0$ V. Access time is determined by the latter of t_{RAC} , t_{CAC} , t_{AA} , t_{CPA} , t_{OEA} . t_{CAC} is measured from tristate.
- 9) Operation within the $t_{RCD (max.)}$ limit ensures that $t_{RAC (max.)}$ can be met. $t_{RCD (max.)}$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD (max.)}$ limit, then access time is controlled by t_{CAC} .
- 10) Operation within the $t_{RAD (max.)}$ limit ensures that $t_{RAC (max.)}$ can be met. $t_{RAD (max.)}$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{RAD (max.)}$ limit, then access time is controlled by t_{AA} .
- 11) Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
- 12) $t_{OFF (max.)}$, $t_{OEZ (max.)}$ define the time at which the output achieves the open-circuit conditions and are not referenced to output voltage levels. t_{OFF} is referenced from the rising edge of RAS or CAS , whichever occurs last.
- 13) Either t_{DZC} or t_{DZO} must be satisfied.
- 14) Either t_{CDD} or t_{ODD} must be satisfied.
- 15) t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{WCS} > t_{WCS (min.)}$, the cycle is an early write cycle and data out pin will remain open-circuit (high impedance) through the entire cycle; if $t_{RWD} > t_{RWD (min.)}$, $t_{CWD} > t_{CWD (min.)}$ and $t_{AWD} > t_{AWD (min.)}$, the cycle is a read-write cycle and I/O will contain data read from the selected cells. If neither of the above sets of conditions is satisfied, the condition of I/O (at access time) is indeterminate.
- 16) These parameters are referenced to the \overline{CAS} leading edge in early write cycles and to the \overline{WE} leading edge in read-write cycles.



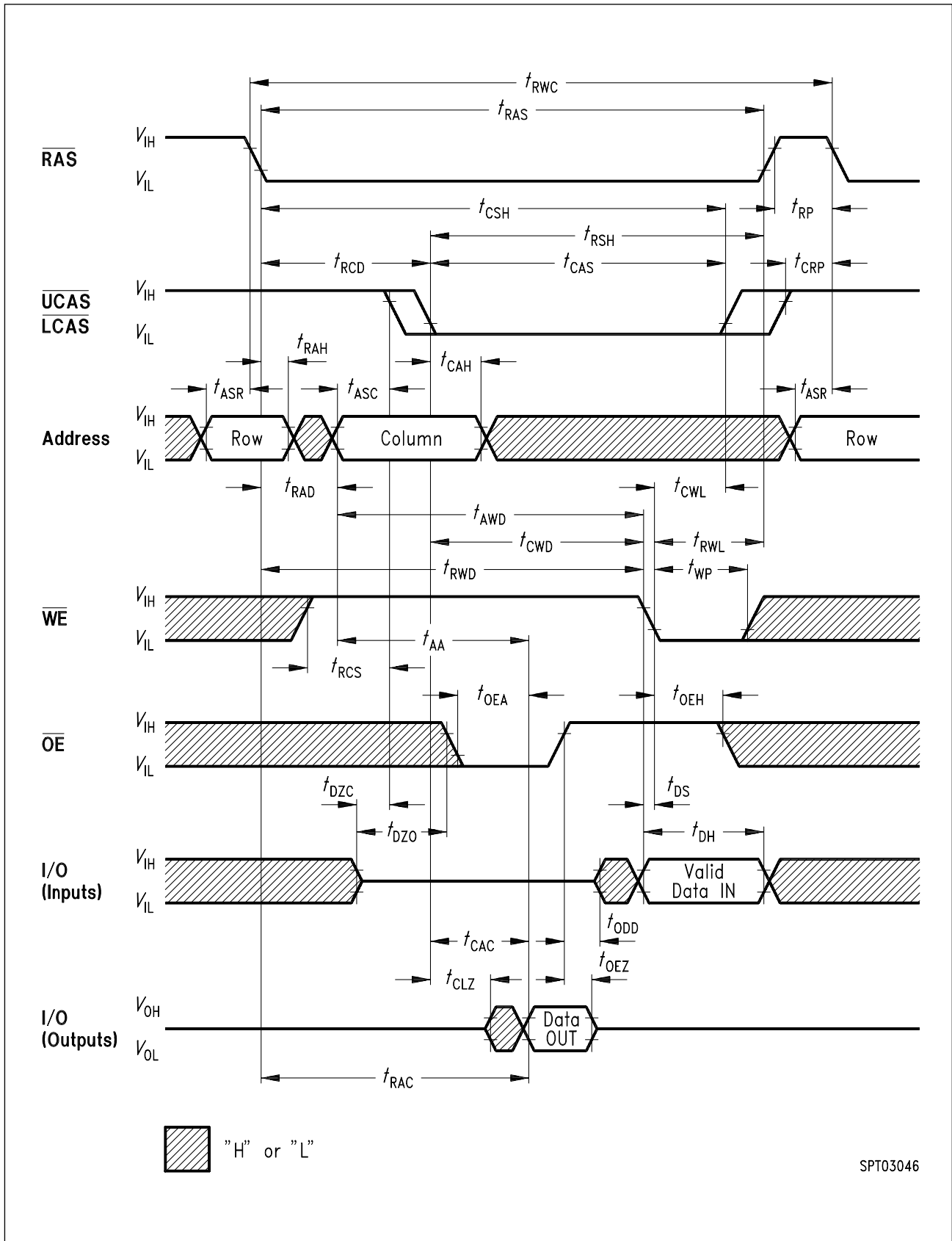
Read Cycle



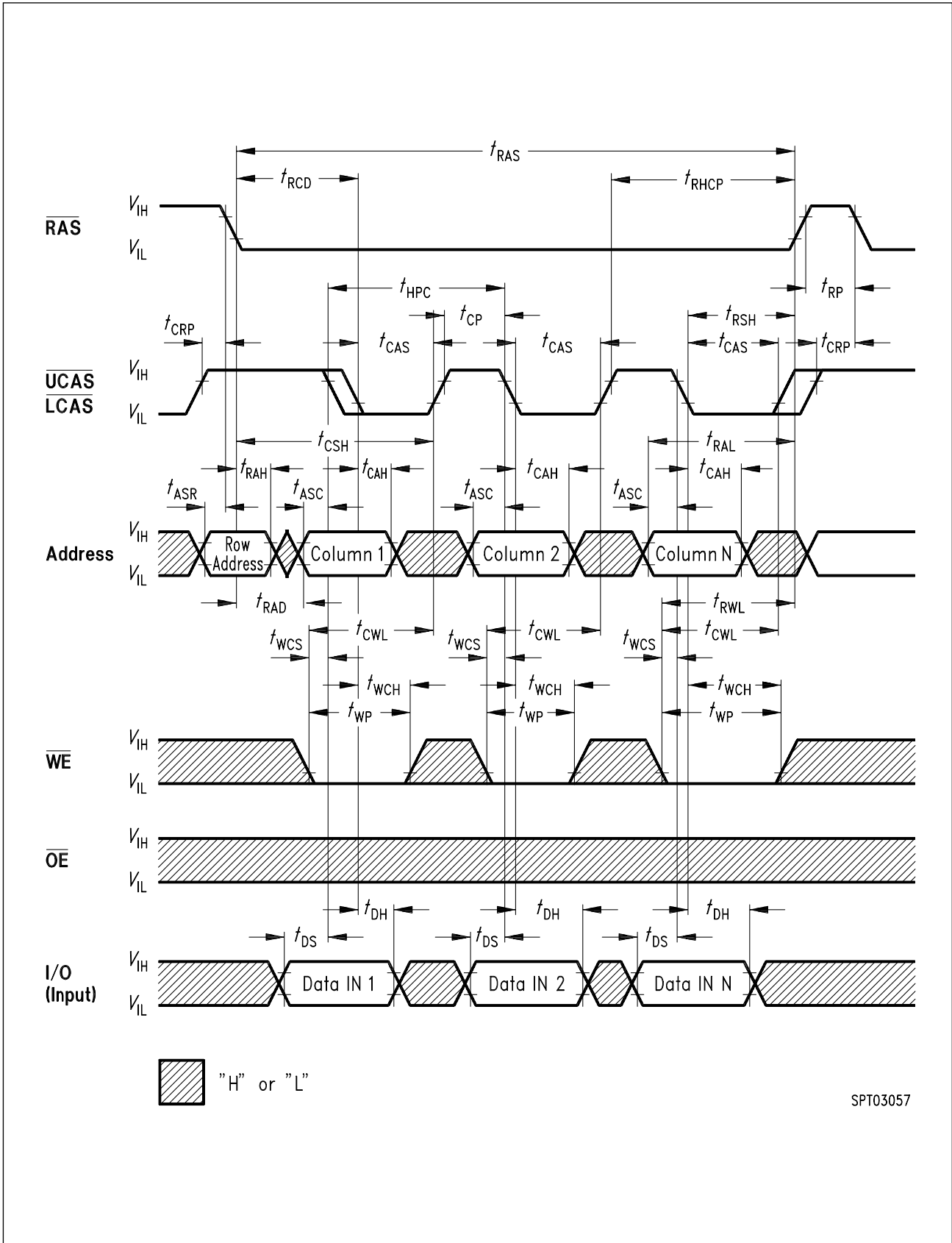
Write Cycle (Early Write)



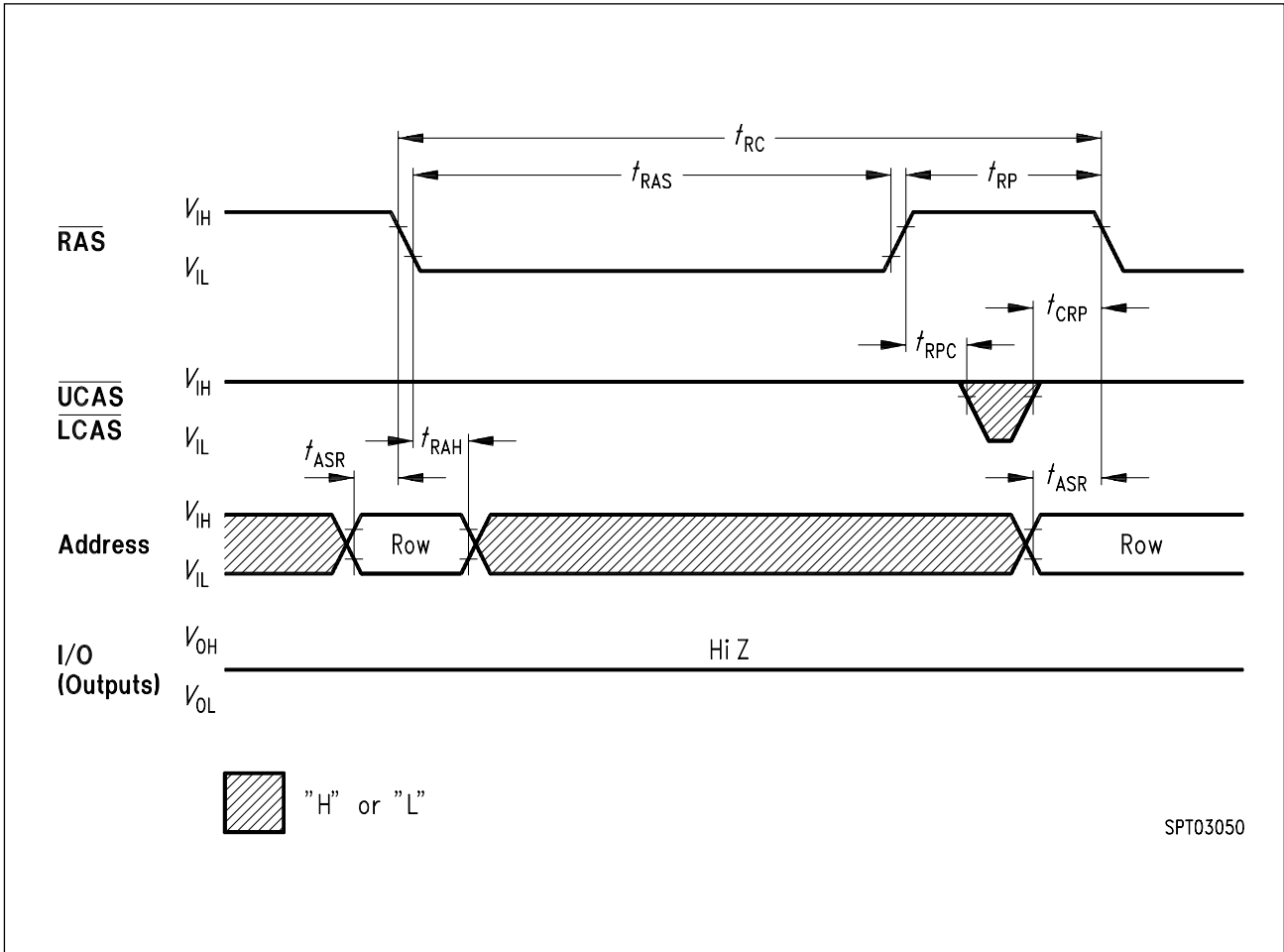
Write Cycle (\overline{OE} Controlled Write)



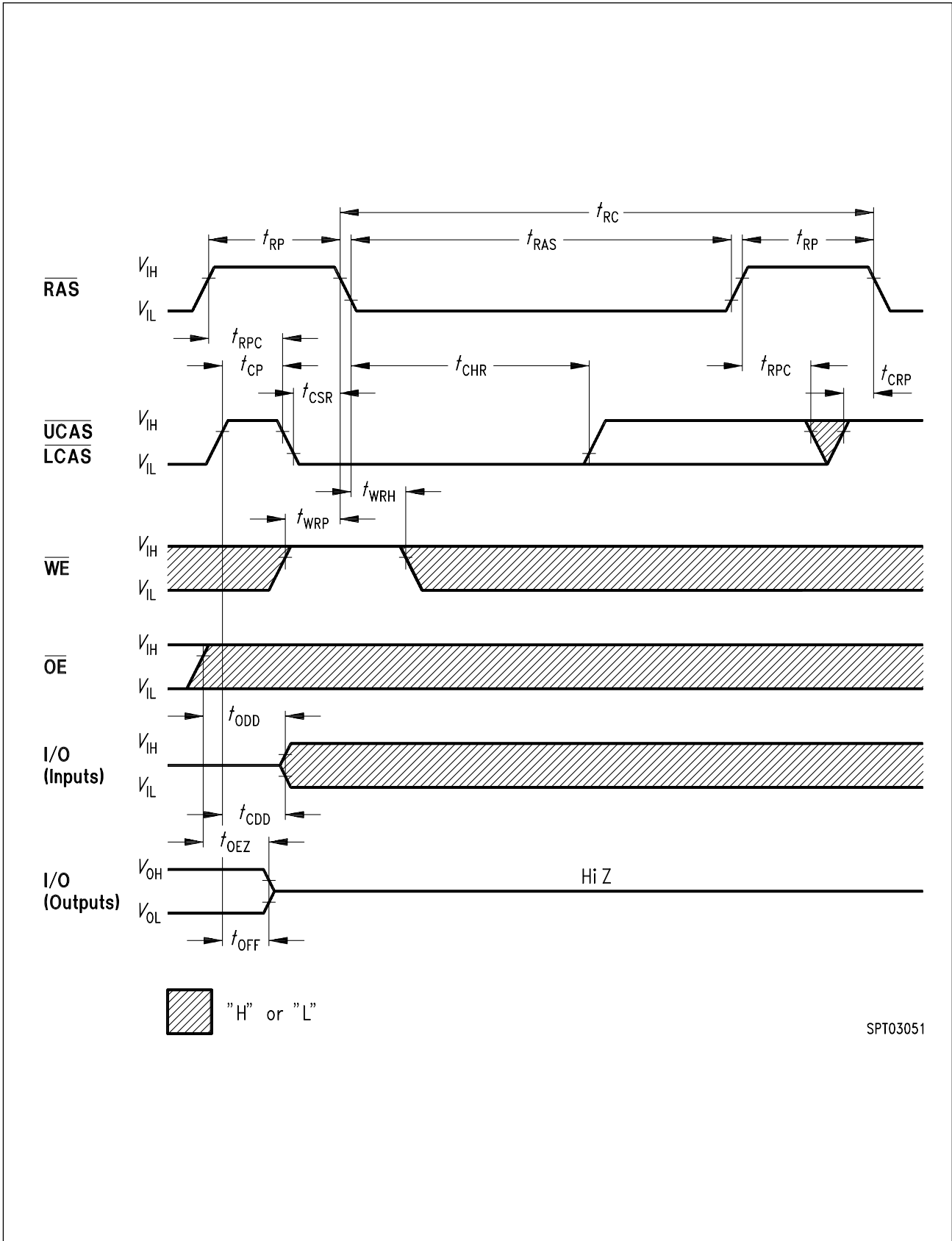
Read-Write (Read-Modify-Write) Cycle



Hyper Page Mode (EDO) Early Write Cycle

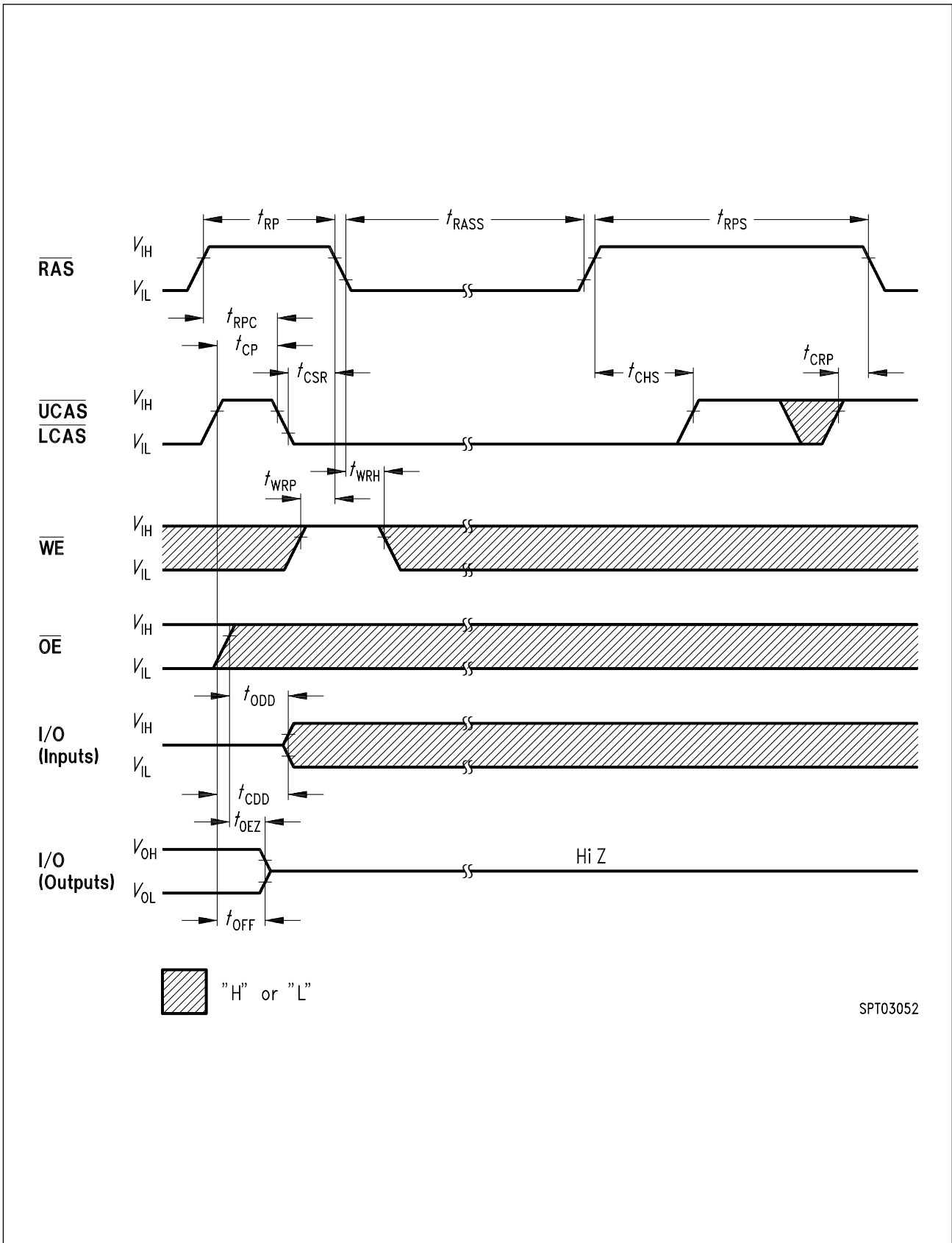


RAS-Only Refresh Cycle

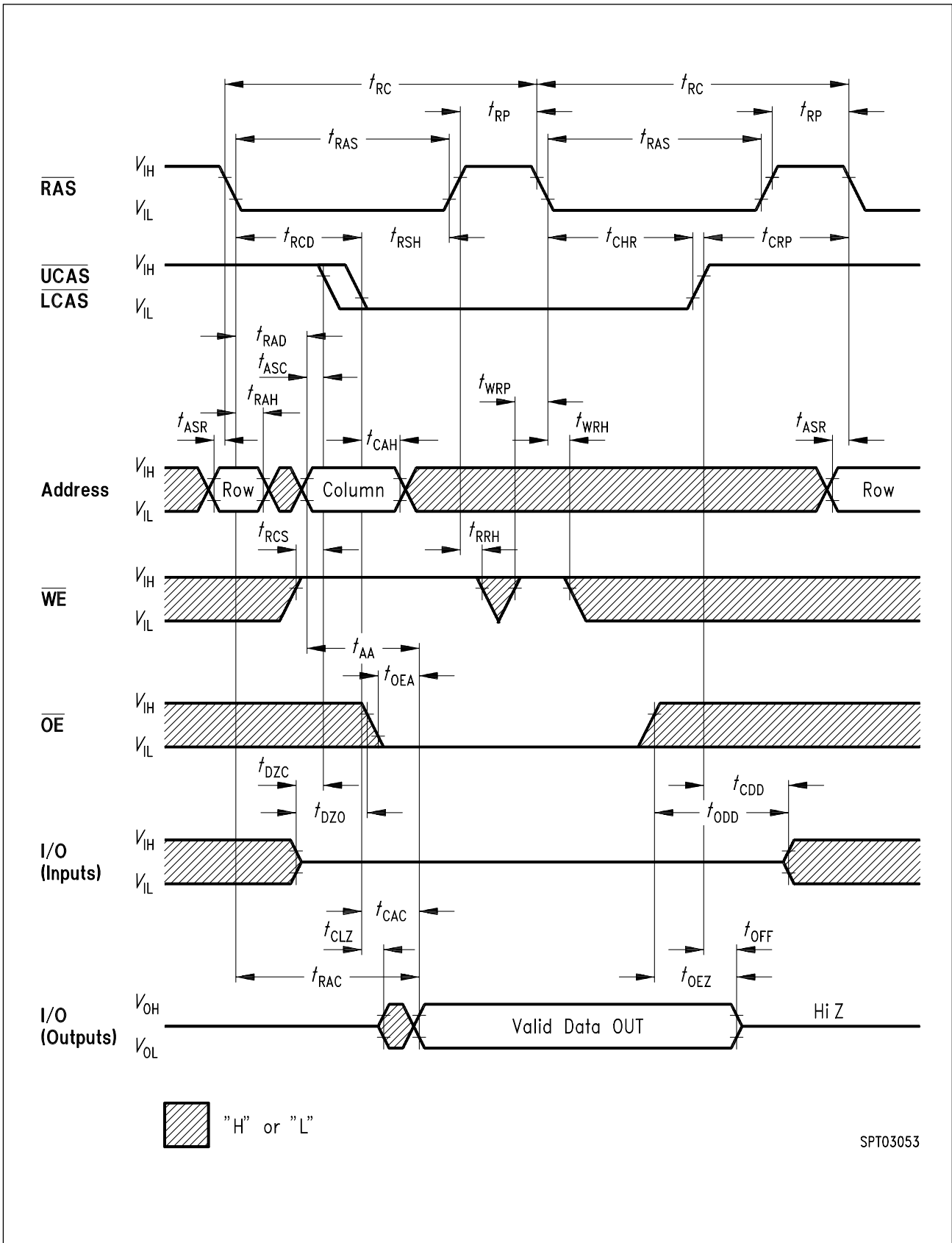


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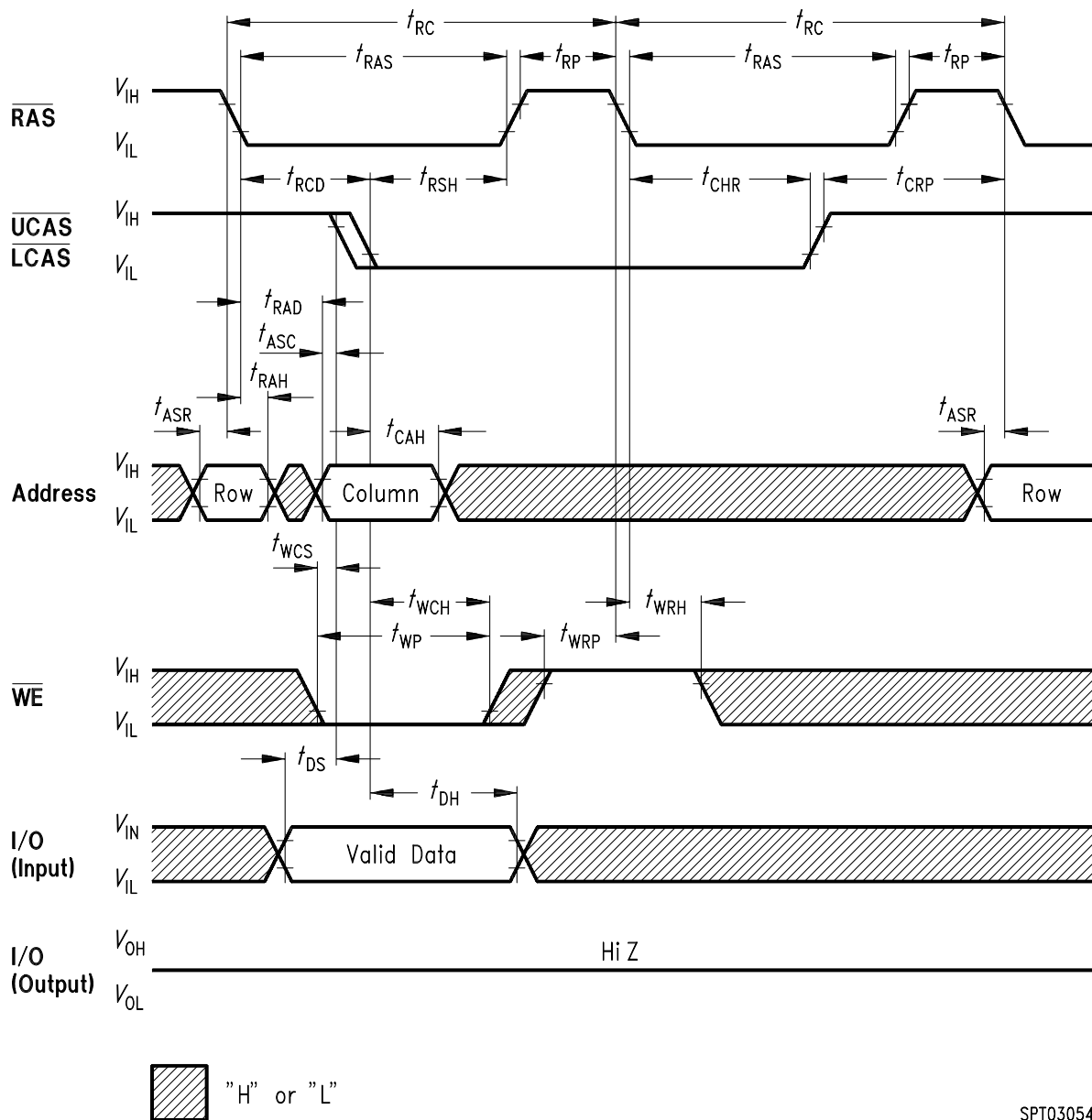
CAS-Before-RAS Refresh Cycle



CAS before RAS Self Refresh Cycle (L-version only)

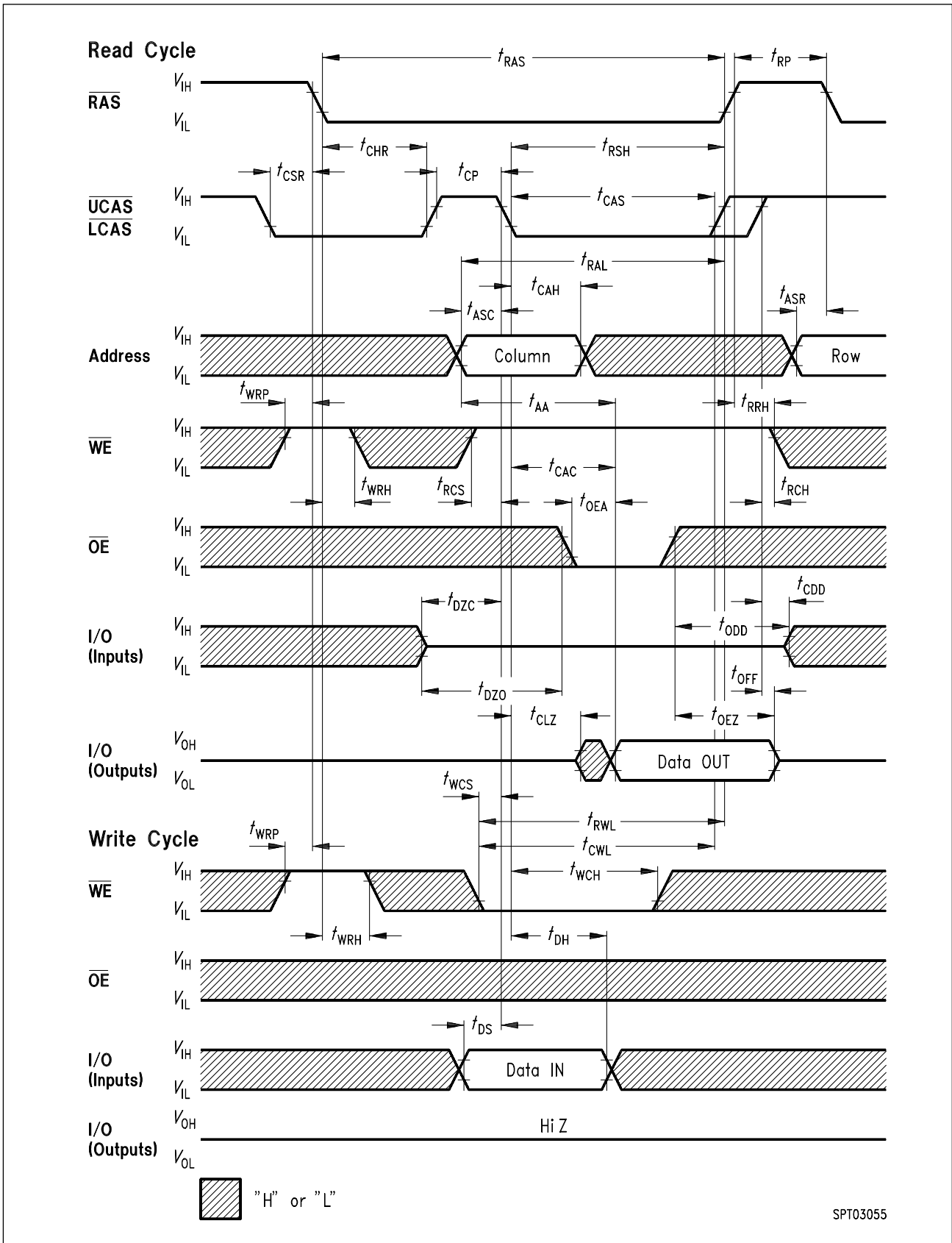


Hidden Refresh Cycle (Read)



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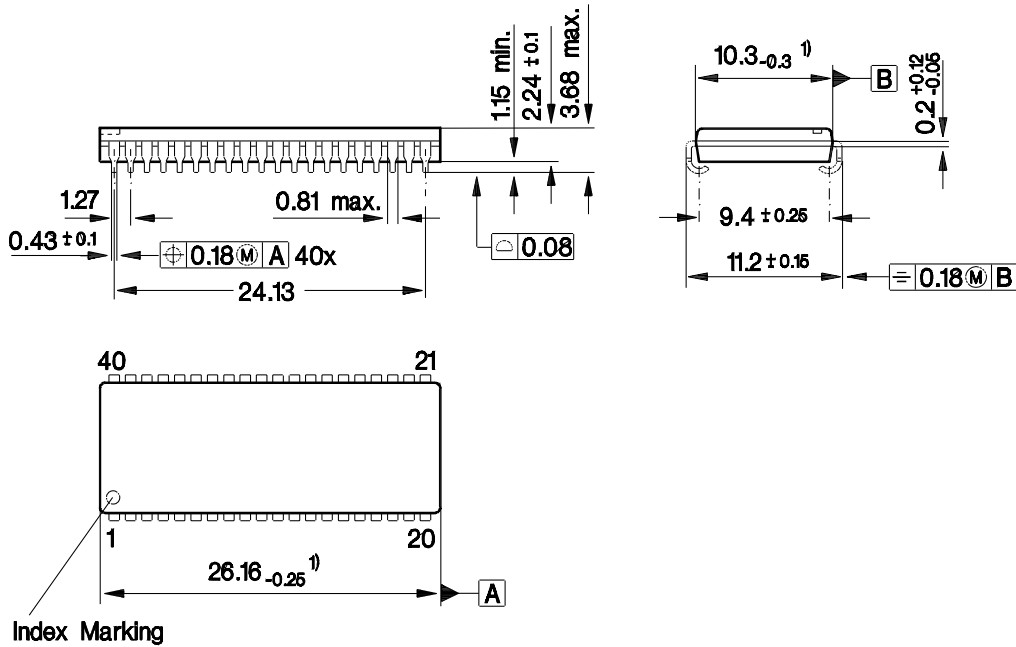
Hidden Refresh Cycle (Early Write)



CAS/Before-RAS Refresh Counter Test Cycle

Package Outline

Plastic Package, P-SOJ- 40-1 (SMD)
(Plastic Small Outline J-leaded Package)



1) Does not include plastic or metal protrusion of 0.25 max. per side

GPJ09018

Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device

Dimensions in mm